2SK1831, 2SK1832

Silicon N-Channel MOS FET

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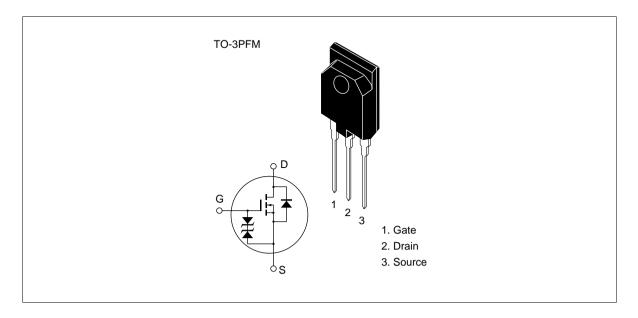
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switchingregulator, DC-DC converter

Outline





2SK1831, 2SK1832

Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item		Symbol	Ratings	Unit	
Drain to source voltage	K1831	$V_{\scriptscriptstyle DSS}$	450	V	
	K1832		500		
Gate to source voltage		V_{GSS}	±30	V	
Drain current	I _D	10	Α		
Drain peak current	l *1 D(pulse)	30	A		
Body to drain diode reverse dra	I _{DR}	10	A		
Channel dissipation	Pch*2	50	W		
Channel temperature	Tch	150	°C		
Storage temperature	Tstg	-55 to +150	°C		

Notes 1. PW \leq 10 μ s, duty cycle \leq 1 %

^{2.} Value at Tc = 25 °C

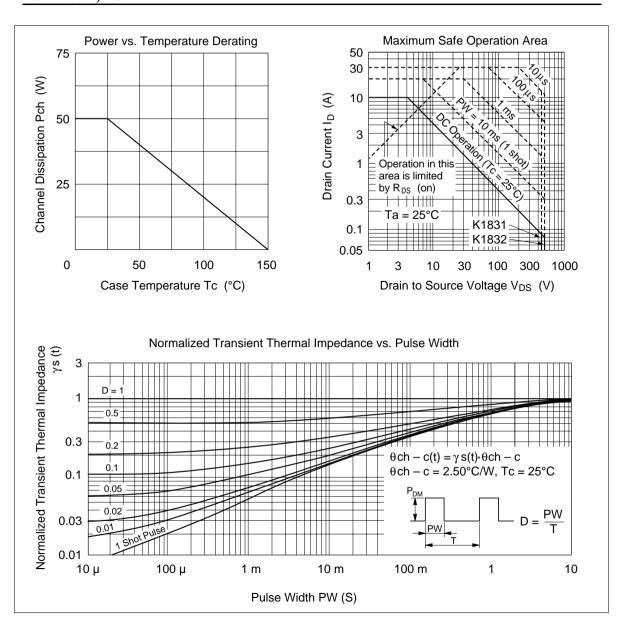
Electrical Characteristics ($Ta = 25^{\circ}C$)

Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source	K1831	$V_{(BR)DSS}$	450	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
breakdown voltage	K1832	_	500	_	_		
Gate to source b	reakdown	$V_{(BR)GSS}$	±30	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source le	eak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate	K1831	I _{DSS}	_	_	250	μΑ	$V_{DS} = 360 \text{ V}, V_{GS} = 0$
voltage drain current	K1832						$V_{DS} = 400 \text{ V}, V_{GS} = 0$
Gate to source c	utoff voltage	$V_{GS(off)}$	2.0	_	3.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to	K1831	R _{DS(on)}	_	0.6	0.8	Ω	I _D = 5 A
source on state resistance	K1832		_	0.7	0.9	_	$V_{GS} = 10 V^{*1}$
Forward transfer	admittance	y _{fs}	4.0	7.0	_	S	$I_D = 5 A$ $V_{DS} = 10 V^{*1}$
Input capacitance	е	Ciss	_	1050	_	pF	V _{DS} = 10 V
Output capacitar	ice	Coss	_	280	_	pF	$V_{GS} = 0$
Reverse transfer	capacitance	Crss	_	40	_	pF	f = 1 MHz
Turn-on delay tin	ne	t _{d(on)}	_	15	_	ns	I _D = 5 A
Rise time		t _r	_	60	_	ns	$V_{GS} = 10 \text{ V}$
Turn-off delay tin	ne	t _{d(off)}	_	90	_	ns	$R_L = 6 \Omega$
Fall time		t _f	_	45	_	ns	
Body to drain did voltage	de forward	V_{DF}	_	1.0	_	V	$I_F = 10 \text{ A}, V_{GS} = 0$
Body to drain did recovery time	de reverse	t _{rr}		350	_	ns	$I_F = 10 \text{ A}, V_{GS} = 0,$ $di_F / dt = 100 \text{ A} / \mu \text{s}$

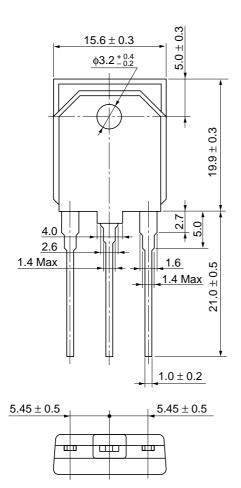
Notes 1. Pulse Test

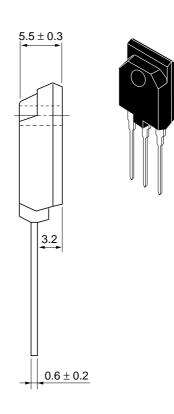
See characteristic curves of 2SK1157, 2SK1158

2SK1831, 2SK1832



Unit: mm





Hitachi Code	TO-3PFM			
JEDEC				
EIAJ				
Weight (reference value)	5.6 g			

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